

## Single Phase 0.5Amp Glass passivated Bridge Rectifiers

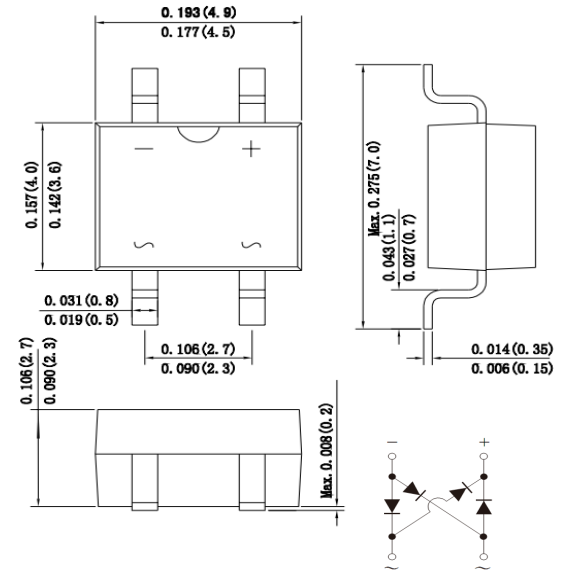
**MBS**


### Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed  
260 °C/10 seconds at terminals

### Mechanical Data

- Case : Molded plastic body
- Terminals : Solder plated, solderable per MIL-STD-750, Method
- 2026 Polarity : Polarity symbol marking on body
- Mounting Position : Any
- Weight : 0.004 ounce, 0.118 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	B05S	B1S	B2S	B4S	B6S	B8S	B10S	Units
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^{\circ}C$ On glass-epoxy P.C.B (Note 1)	$I_{(AV)}$	0.5							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	25.0							A
Rating for fusing (t=8.3ms, $T_A=25^{\circ}C$ )	$I_t^2$	2.59							$A^2_s$
Maximum instantaneous forward voltage at 0.5A	$V_F$	1.0							V
Maximum DC reverse current $T_A=25^{\circ}C$ at rated DC blocking voltage $T_A=125^{\circ}C$	$I_R$	2.0 200							$\mu A$
Typical junction capacitance (Note 2)	$C_J$	13.0							pF
Typical thermal resistance	$R_{qJA}$	72.0							$^{\circ}C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^{\circ}C$

Note: 1. Mounted on glass epoxy PC board with 1.3\*1.3mm solder pad

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.



Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

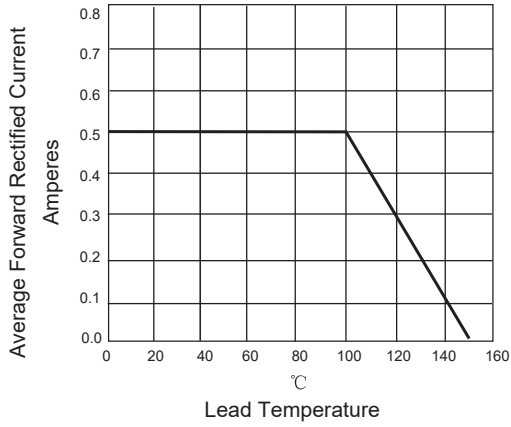


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

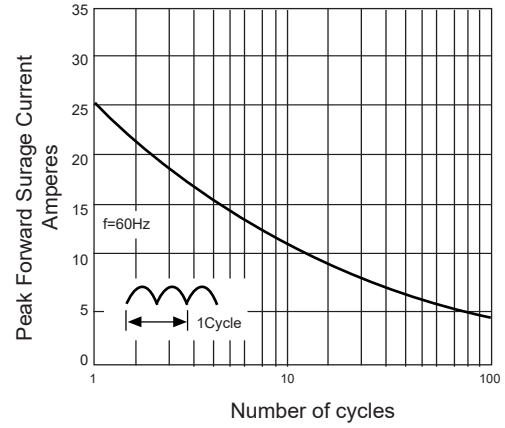


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

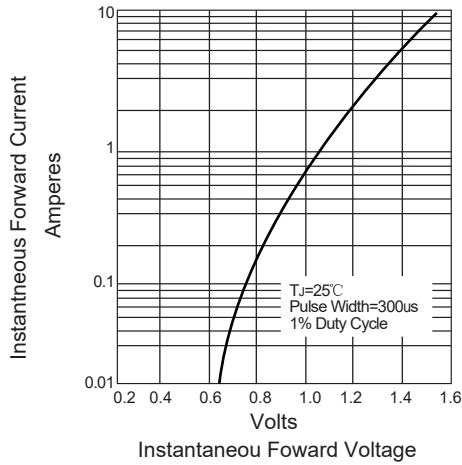
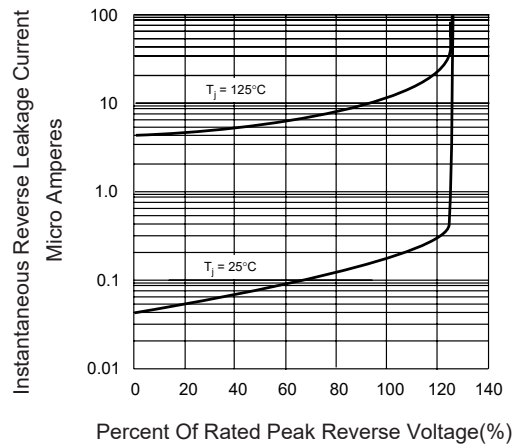
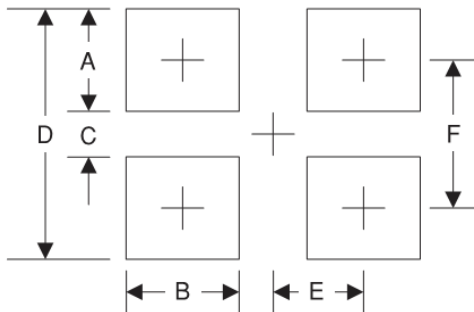


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



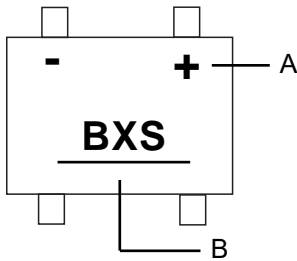
Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.7	0.067
B	1.0	0.039
C	4.40	0.173
D	8.10	0.319
E	1.25	0.049
F	6.30	0.248

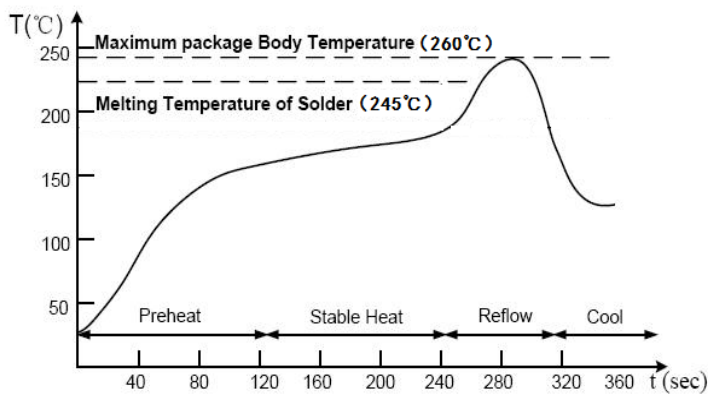


## Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name, X : 05, 1.....10

## Suggested Soldering Temperature Profile

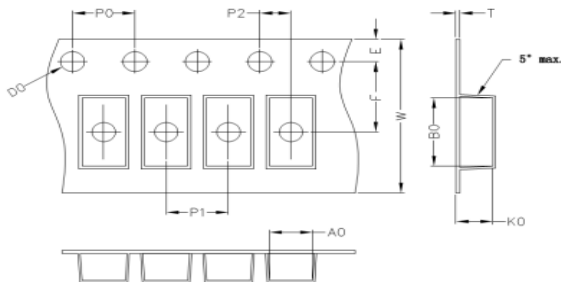


### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

### Carrier Dimension(mm)



A0	B0	K0	D0	E	F
5.10	7.20	2.88	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MBS	13'	330	3	338	6	365*365*360	48